

VIGON® A 201

Water-based defluxing agent for high pressure cleaning processes



VIGON® A 201, based on the MPC® Technology, is a water-based cleaning agent specifically developed for high pressure spray-in-air processes with short exposure times. It is recommended for removing a wide range of flux residues from electronic assemblies.

Areas of application: PCB cleaning		Additional product information:
Low solid flux residues	++	Application Recommendation: Specific parameters for your cleaning process Technical Information 2: Overview of all fluxes and solder pastes tested Technical Information 3: Material compatibility overview MPC® Technology Sheet: Additional information on MPC® Technology
Rosin-based flux residues	++	
Water soluble flux residues	++	
Solder pastes (unsoldered)	+	
SMT or conductive adhesives	0	

++ highly recommended, best results

+ recommended

0 possible

Technical Centers - ① America ② Europe ③ Malaysia ④ East China ⑤ South China Cleaning Process Solutions under Production Floor Conditions



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
Phone: +1 (703) 393-9880; Email: infoUSA@zestron.com

Advantages compared to other surfactant cleaners:

- Specifically developed for inline cleaning applications.
- Ability to clean a wide range of flux residues.
- Excellent cleaning results even in cleaning processes with short exposure time.
- High bath loading capacity ensures an extended bath life, low maintenance costs and reduced costs per cleaned part.
- Surfactant-free formulation eliminates the formation of white residues on cleaned parts as well as cleaning equipment and eliminates time-consuming surfactant monitoring.
- Does not foam, even in high pressure applications.
- Halogen free.

Please refer to the material compatibility datasheet (Technical Information 3) prior to cleaning plastics.



Process	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air (Inline/Batch)	VIGON® A 201	DI-water	Hot or circulated air
Centrifugal cleaning/ Ultrasonic	VIGON® A 201	DI-water	Hot or circulated air

Technical Data: VIGON® A 201 at 15 % concentration.		
Density	(g/ccm) at 20°C/68°F	1.00
Surface tension	(mN/m) at 25°C/77°F	28.7
Boiling range	°C/°F	> 100 / 212
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	10.51
Vapor pressure	(mbar) at 20°C/68°F	20
Cleaning temperature	°C/°F	40 - 70 / 104 - 158
Solubility in water		Soluble
Application concentration	%	10 - 20
HMS rating	Health-Flammability-Reactivity	1 - 0 - 0

PRODUCT FEATURES



Extensively tested and suitable for cleaning of LF solder pastes



MPC® Technology ensures an extremely long bath life when processed closed loop



100% compliance with EU guidelines



Product is free of any critical substances according to SIN & SVHC lists

Environmental, health and safety regulations:

- VIGON® A 201 is water-based and biodegradable.
- It does not contain any halogenated compounds.
- VIGON® A 201 is a non-hazardous material.

Availability:

- VIGON® A 201 is available as a concentrate in 1L, 5L or 25L containers and 200L drums.

Storage:

- Store VIGON® A 201 in the original container at a temperature between 5-30°C / 41-86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For water-based defluxing of electronic assemblies in low and / or medium pressure spray-in-air processes, we also recommend VIGON® A 250.